

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

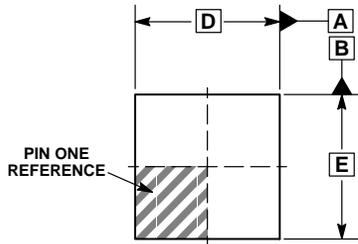
ON Semiconductor®



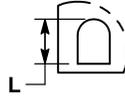
SCALE 4:1

XDFN6 1.20x1.20, 0.40P
CASE 711AT
ISSUE C

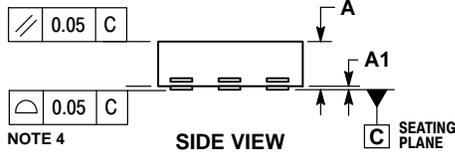
DATE 04 DEC 2015



TOP VIEW

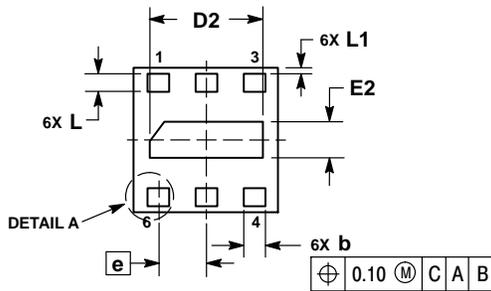


DETAIL A
OPTIONAL
CONSTRUCTION



SIDE VIEW

NOTE 4



BOTTOM VIEW

NOTE 3

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO THE PLATED TERMINALS.
4. COPLANARITY APPLIES TO THE PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN | TYP | MAX |
| A | 0.30 | 0.37 | 0.45 |
| A1 | 0.00 | 0.03 | 0.05 |
| b | 0.13 | 0.18 | 0.23 |
| D | 1.15 | 1.20 | 1.25 |
| D2 | 0.84 | 0.94 | 1.04 |
| E | 1.15 | 1.20 | 1.25 |
| E2 | 0.20 | 0.30 | 0.40 |
| e | 0.40 BSC | | |
| L | 0.15 | 0.20 | 0.25 |
| L1 | 0.00 | 0.05 | 0.10 |

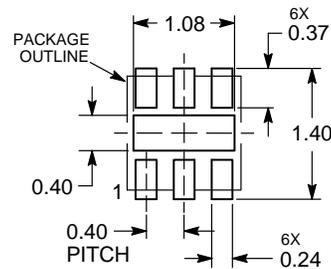
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | XDFN6, 1.20 X 1.20, 0.40P | PAGE 1 OF 2 |

